NXP Semiconductors

Product Brief Rev 2.0

NXP USB Stack Product Brief

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1. Software Product Overview

The USB stack is an implementation of the USB standard. It is a port of the Kinetis USB stack on NXP's automotive processors.

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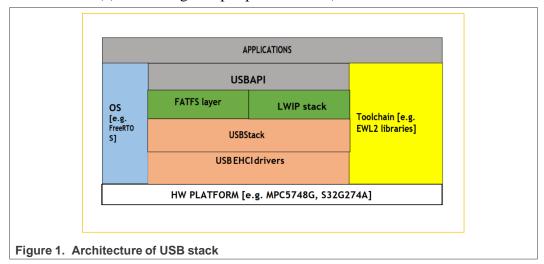
The current implementation supports:

- Mass storage devices on both the host controller and the OTG interface. The file system is an open source project, supported by Elm Chan and for the latest news andreleases please check: http://elm-chan.org/fsw/ff/00index_e.html.
- USB CDC-ECM communication model running on both the host controller and OTG interface (stack acting as a host)

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• USB CDC peripheral/device mode (communication through Virtual Serial COM Port)(stack acting as a peripheral/device)



2. Software Content

The USB stack API consists of three parts:

- **USB API:** implementing USB specific instructions
- **FATFS API:** implementing file system functionality. This layer is independent of the USB stack and it uses disk I/O operations to communicate with the mass storage device.
- **LWIPAPI:** implementing ENET read/write functionality. This layer is dependent on the USB stack, as it reads and writes packets on the USB port.

3. Supported Targets

The following table shows the supported platforms for USB stack.

Table 1. Supported platforms, toolchains, etc.

| Product | Devices | Toolchains | IDEs | Supported NXPSoftwares | os |
|---------------------------|----------|------------------------|-------------------|-----------------------------------|-----------|
| USB stack for MPC574XG | MPC574XG | GNU C, GHS, DIAB | S32 Design Studio | SDK drivers for MPC57XX family | Baremetal |
| USB stack for S32G2 | S32G2 | GNU C, GHS, DIAB | S32 Design Studio | RTD for S32G | Baremetal |
| USB stack for S32G3 | S32G3 | GNU C, GHS, DIAB | S32 Design Studio | RTD for S32G | Baremetal |

4. Quality, Standards Compliance and Testing Approach

USB Stack is developed according to NXP Software Development Processes that are Automotive-SPICE, IATF 16949 and ISO9001 compliant.

5. Document Information

Table 2. Revision History

| Revision | Date | Description |
|----------|------------|-----------------|
| Rev 1.0 | 07/07/2021 | Initial version |
| Rev 2.0 | 02/07/2023 | Update |

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